

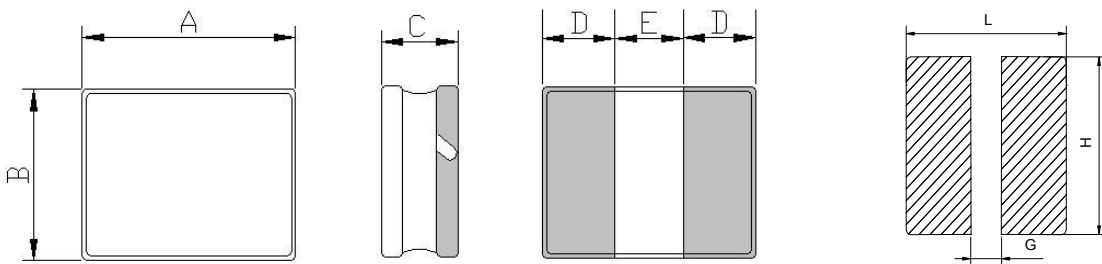
1. Part No. Expression:

S P A 2 0 1 6 1 0 F A □ □ □ M

(a) (b) (c) (d) (e)

- a) Series Code
- b) Dimension Code
- c) Type Code
- d) Inductance Code
- e) Tolerance Code

2. Configuration & Dimensions:

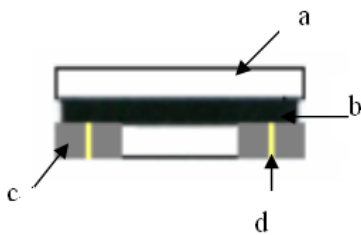


Recommended PC Board Pattern

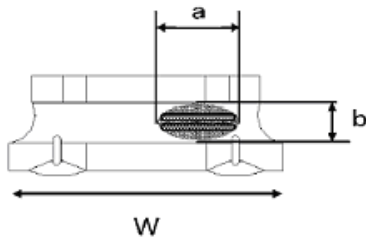
Unit: mm

A	B	C	D	E	L	G	H
2.0 +0.2/-0.1	1.6 +0.2/-0.1	1.0 Max.	0.5 Ref.	1.0 Ref.	2.3 Ref.	0.8 Ref.	1.9 Ref.

3. Material List:



- (a) Core
- (b) Glue
- (c) Termination
- (d) Wire



Appearance of exposed wire tolerance limit:

1. Width direction (dimension a) : Acceptable when $a \leq w/2$
Non-acceptable when $a > w/2$
2. Length direction (dimension b) : Dimension b is not specified.
3. The total acceptable area of exposed wire occurring to each sides is no greater than 50% of coating resin area.

NOTE: Specifications subject to change without notice. Please check our website for latest information.



4. General Specification:

- (a) Operating Temp. : -40°C to +125°C (including self-temperature rise)
- (b) Storage Temp. : -40°C to +125°C (on board)
- (c) Irms. : Based on temperature rise (ΔT : 40°C.) Max.
- (d) Isat. : Based on inductance change ($\Delta L/L0$: $\leq 30\%$.)
- (e) Storage condition (component in its packaging)
 - i) Temperature: Less than 40°C
 - ii) Humidity : 60% RH

5. Electrical Characteristics:

Part Number	Inductance (μ H) $\pm 20\%$	Test Frequency (Hz)	DCR (Ω) Typ.	DCR (Ω) Max.	I sat (A) Typ.	I sat (A) Max.	I rms (A) Typ.	I rms (A) Max.
SPA201610FAR24M	0.24	1V/1M	0.015	0.020	7.50	6.50	5.70 (1) 6.50 (2)	5.10 (1) 5.50 (2)
SPA201610FAR33M	0.33	1V/1M	0.018	0.023	5.50	5.00	5.50 (1) 5.60 (2)	5.00 (1) 5.20 (2)
SPA201610FAR47M	0.47	1V/1M	0.024	0.029	5.20	4.50	4.70 (1) 5.30 (2)	4.30 (1) 4.70 (2)
SPA201610FAR68M	0.68	1V/1M	0.036	0.044	5.10	4.40	3.90 (1) 4.20 (2)	3.50 (1) 3.80 (2)
SPA201610FA1R0M	1.0	1V/1M	0.050	0.060	4.50	4.00	3.20 (1) 3.40 (2)	2.90 (1) 3.10 (2)
SPA201610FA1R5M	1.5	1V/1M	0.068	0.082	3.20	2.80	2.90 (1) 3.10 (2)	2.50 (1) 2.70 (2)
SPA201610FA2R2M	2.2	1V/1M	0.100	0.120	2.70	2.40	2.20 (1) 2.30 (2)	2.00 (1) 2.10 (2)
SPA201610FA4R7M	4.7	1V/1M	0.180	0.216	1.60	1.40	1.60 (1) 1.80 (2)	1.40 (1) 1.60 (2)

Tolerance code : M = 20%

For Irms (A) Max. values with '(1)' or '(2)', refer to notes below for board test conditions.

Notes:

1) At all times, the current supplied to the product should not exceed Irms Max. value

2) Irms Max. board test conditions:

Irms (1)

Material: FR4

Board dimensions: 100 X 50 X 1.6t mm

Pattern dimensions: 45 X 30 mm (Double side board)

Pattern thickness: 50 μ m

Irms (2)

Material: FR4

Board dimensions: 100 X 50 X 1.6t mm

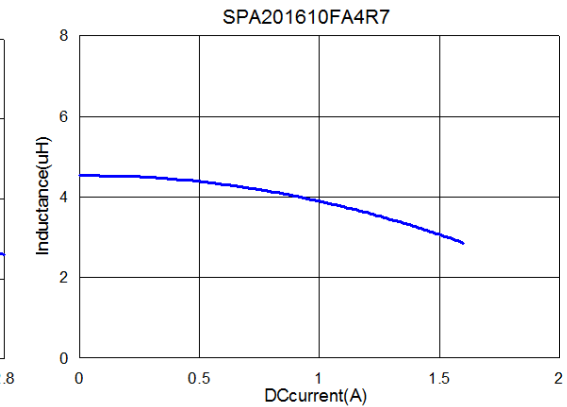
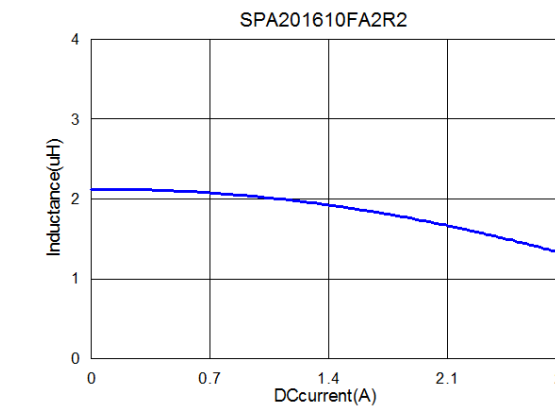
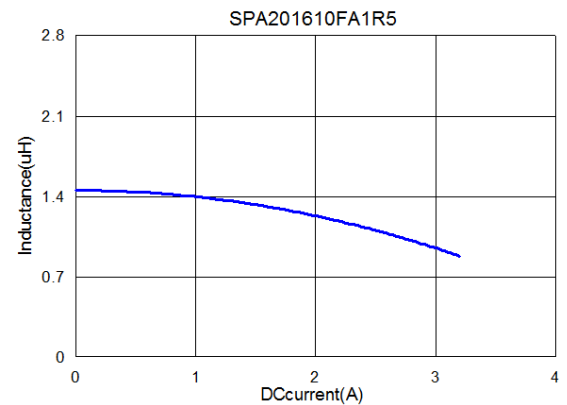
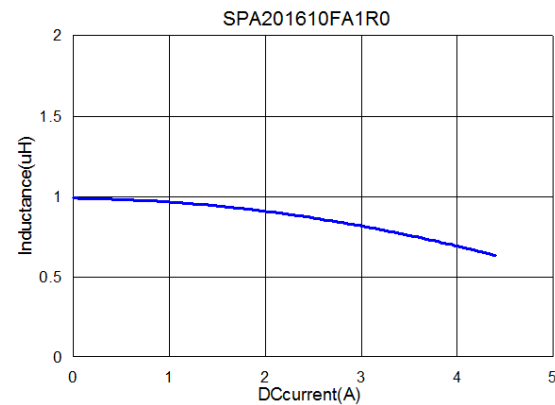
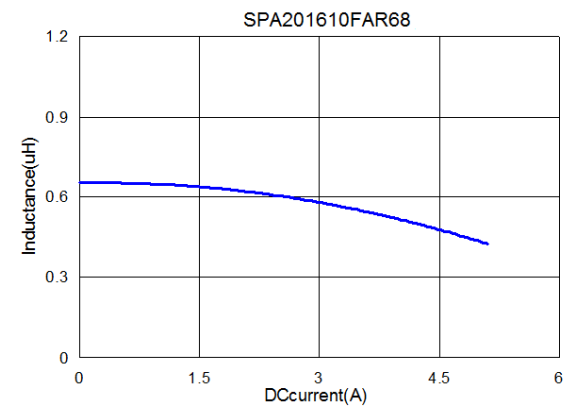
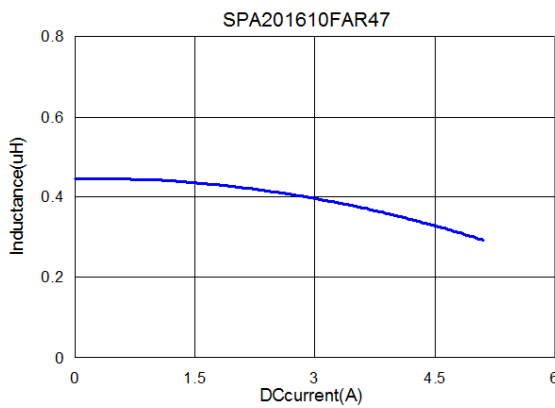
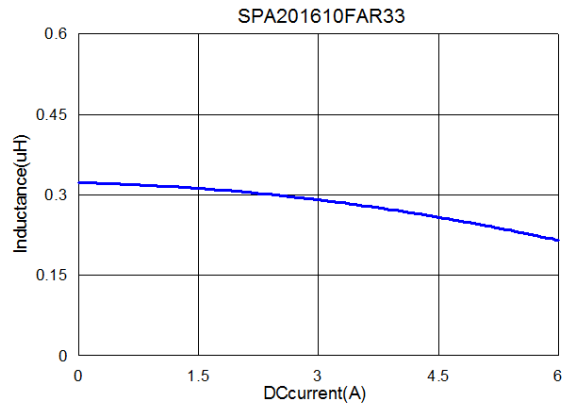
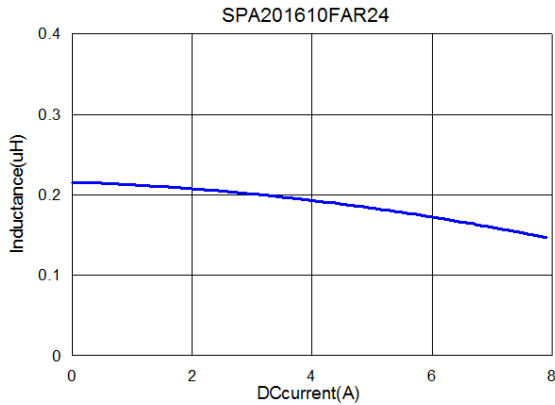
Pattern dimensions: 45 X 45 mm (Double side board)

Pattern thickness: 70 μ m

NOTE: Specifications subject to change without notice. Please check our website for latest information.



6. Characteristics Curves:



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7. Soldering:

Mildly activated rosin fluxes are preferred. Our terminations are suitable for all re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

7-1 Solder Re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

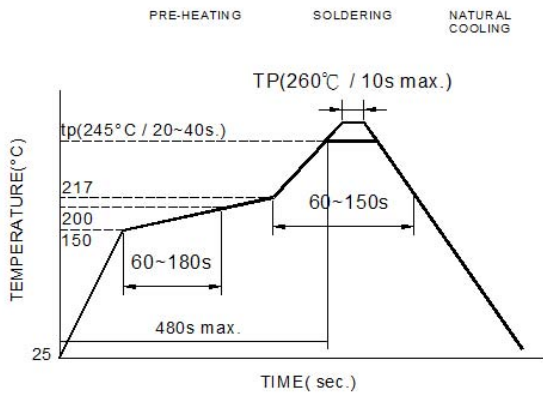
7-2 Soldering Iron (Figure 2):

Products attachment with soldering iron is discouraged due to the inherent process control limitations.

In the event that a soldering iron must be employed the following precautions are recommended.

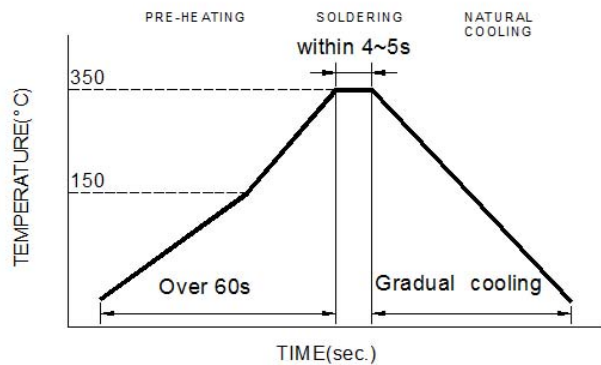
Note :

- a) Preheat circuit and products to 150°C.
- b) 355°C tip temperature (Max.)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (Max.)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 4~5 secs.



Reflow times: 3 times max.

Fig.1



Iron Soldering times: 1 times max.

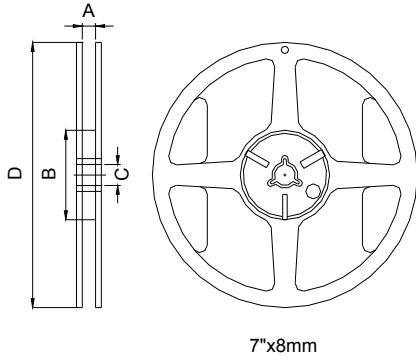
Fig.2

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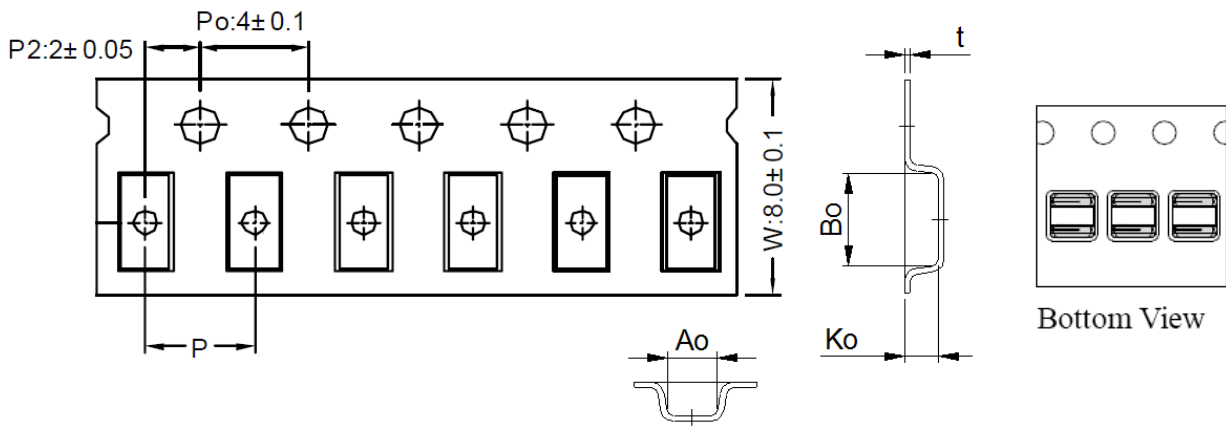
8. Packaging Information:

8-1 Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
7"x8mm	8.4±1.0	50 Min.	13±0.8	178±2

8-2 Tape Dimension



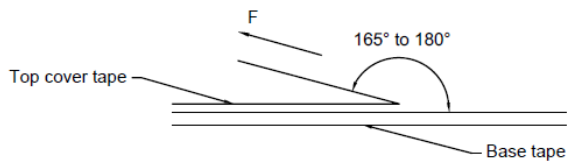
Series	Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
SPA	201610	2.50±0.1	2.00±0.1	1.40±0.1	4.00±0.1	0.23±0.05

8-3 Packaging Quantity

Chip size	201610
Chip / Reel	2000

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8-4 Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice:

1. Storage Conditions:

To maintain the solderability of terminal electrodes:

- a) Recommended products should be used within 12 months from the time of delivery.
- b) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) Vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.

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